SDIA3012 TYPE

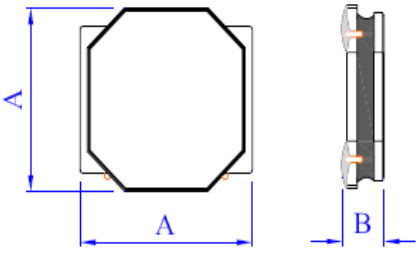
●FEATURE

1. Low profile and small size (Height: 1.20mm Max)
2. Low DC resistance

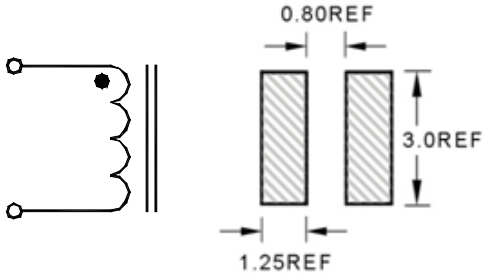
●Applications

1. LCD panels
2. Digital camera , PDA and others

●Shape and Dimension



●Schematics and Land Patterns(mm)



A=3.00±0.20m/m ; B= 1.20m/m MAX ; C= 1.60m/m REF.

●Specification

Part Number	L(uH)	DCR(ΩMax)	Isat(mA)	Irms(mA)
SDIA3012-1R0N	1.0±30%	0.0672	1500	1490
SDIA3012-1R5N	1.5±30%	0.072	1360	1400
SDIA3012-2R2M	2.2±20%	0.096	1100	1200
SDIA3012-3R3M	3.3±20%	0.120	910	1050
SDIA3012-4R7M	4.7±20%	0.192	770	980
SDIA3012-6R8M	6.8±20%	0.282	670	740
SDIA3012-100M	10±20%	0.348	540	630
SDIA3012-150M	15±20%	0.540	440	485
SDIA3012-220M	22±20%	0.756	375	420
SDIA3012-330M	33±20%	1.236	310	330
SDIA3012-470M	47±20%	1.740	250	280

Note1. Measurement frequency of Inductance value : at 100KHz, 0.25V

Note2. Measurement ambient temperature of L, DCR and IDC : at 25℃

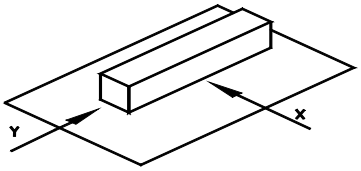
Note3. Isat : △L/L≦30%(This indicates the value of current when the inductances is 30% lower than its initial value at D.C. superimposition)

Note4. Irms : D.C. current when at Δt=40℃(typ.).(Ta=25℃)

Note5.Packaging: Taping ; Quantity: 2000 Pieces/reel

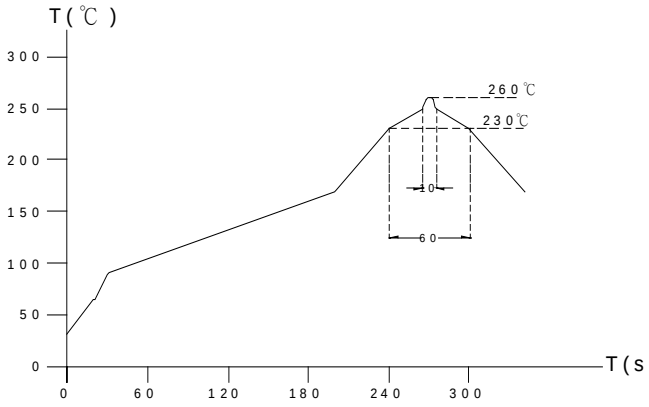
GENERAL CHARACTERISTICS

1. Operating temperature range: -40 TO + 105℃(Includes temperature when the coil is heated)
2. External appearance: On visual inspection, the coil has no external defects.
3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.
   Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.



4. Insulating resistance: Over 100MΩ at 100V D.C. between coil and core.
5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
6. Temperature characteristics: Inductance coefficient (0~2,000)x10-6/℃(-25~+80℃).
7. Humidity characteristics(Moisture Resistance): Inductance deviation within ±5%, after 96 hours in 90~95% relative humidity at 40 ±2℃and 1 hour drying under normal condition.
8. Vibration resistance: Inductance deviation within ±5%, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
9. Shock resistance: Inductance deviation within ±5%, after being dropped once with 981m/s2 (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
10. Resistance to Soldering Heat: 260℃, 10 seconds(See attached recommend reflow)
11. Storage environment: Storage condition: Temperature Range: 10℃ ~ 35℃ (Generally: 21℃ ~ 31℃) , Humidity Range: 50% ~ 80% RH (Generally: 65% ~ 75%) ; Transportation condition: Temperature Range: -35℃ ~ 85℃ , Humidity Range: 50% ~ 95% RH
12. Use components within 6 months. If 6 months or more have elapsed, check solderability before use.
13. Reflow profile recommend:

Lead-free heat endurance test



Lead-free the recommended reflow condition

